

Title (en)
Copper, copper alloy, and manufacturing method therefor


Title (de)
Kupfer sowie Kupferlegierung und Verfahren zur Herstellung

Title (fr)
Cuivre et alliage de cuivre et procédé de fabrication

Publication
EP 1245690 B1 20061011 (EN)

Application
EP 02006886 A 20020326

Priority
JP 2001091179 A 20010327

Abstract (en)
[origin: EP1245690A1] Copper and copper alloy comprises: a structure having fine crystal grains with grain size of 1 μm or less after a final cold rolling with a reduction η , wherein η is expressed in the following formula and satisfying $\eta \geq 3$; and an elongation of 2% or more in a tensile test. $\langle DF \rangle \eta = \ln (T_0/T_1)$ $\langle DF \rangle$ T0: plate thickness before rolling, T1: plate thickness after rolling. 

IPC 8 full level
C22C 9/00 (2006.01); **C22F 1/08** (2006.01); **B21B 3/00** (2006.01)

CPC (source: EP KR US)
B21B 3/00 (2013.01 - EP US); **C22C 9/00** (2013.01 - KR); **C22F 1/08** (2013.01 - EP US); **B21B 2003/005** (2013.01 - EP US)

Cited by
DE112005001197B4

Designated contracting state (EPC)
CH DE FR IT LI SE

DOCDB simple family (publication)
EP 1245690 A1 20021002; **EP 1245690 B1 20061011**; CN 1223690 C 20051019; CN 1386873 A 20021225; DE 60215240 D1 20061123; DE 60215240 T2 20070503; KR 100513943 B1 20050909; KR 20020076139 A 20021009; US 2002189729 A1 20021219; US 2008277032 A1 20081113

DOCDB simple family (application)
EP 02006886 A 20020326; CN 02119270 A 20020327; DE 60215240 T 20020326; KR 20020016015 A 20020325; US 10545402 A 20020326; US 13404308 A 20080605